

REQUEST FOR PROPOSALS

ADDENDUM #1

ISSUED: 7/28/15

RFP NUMBER: CSP903216
INDEX NUMBER: DEV015

The state of Ohio, through the Department of Administrative Services, Office of Procurement Services, on behalf of the Ohio Development Services Agency, Office of Technology Investments is requesting Proposals for:

Contractor Evaluation Services for
Ohio Third Frontier Pre-Seed/Seed Plus Fund Capitalization Program

Attached is page 1 to this Request for Proposal (RFP). Remove the corresponding page from the existing RFP and replace with the attached.

Reason for Addendum. This addendum is issued to extend the Proposal date to August 5, 2015.

PROPOSAL DUE DATE:
OPENING LOCATION:

August 5, 2015 by 1:00PM
Department of Administrative Services
General Services Bid Desk
4200 Surface Road
Columbus, Ohio 43228-1395

REQUEST FOR PROPOSALS

REQUEST FOR PROPOSAL

RFP NUMBER: CSP903216
 INDEX NUMBER: DEV015
 UNSPSC CATEGORY: 80101500

The state of Ohio, through the Department of Administrative Services, Office of Procurement Services, on behalf of the Ohio Development Services Agency, Office of Technology Investments is requesting Proposals for:

Contractor Evaluation Services for
 Ohio Third Frontier Pre-Seed/Seed Plus Fund Capitalization Program

OBJECTIVE: The Ohio Development Services Agency's (Development) Office of Technology Investments is requesting proposals from Offerors to provide services and other forms of technical assistance related to review of proposals submitted for funding under the Ohio Third Frontier's Pre-Seed/Seed Plus Fund Capitalization Program for State fiscal years (FY) 2016 and 2017.

RFP ISSUED:	July 11, 2015
INQUIRY PERIOD BEGINS:	July 11, 2015
INQUIRY PERIOD ENDS:	July 22, 2015 at 8:00 AM
PROPOSAL DUE DATE:	*August 5, 2015 by 1:00 PM

Proposals received after the due date and time will not be evaluated.

Submit Sealed Proposals to:

Department of Administrative Services
 Office of Procurement Services
 Attn: Bid Desk
 4200 Surface Road
 Columbus, OH 43228-1395

Note: Please review the [Proposal Instructions](#) on our Web site.

The Offeror must submit this cover page (signed) with its Technical Proposal.

<p>Offeror Name and Address:</p> <hr/> <hr/> <hr/> <hr/> <hr/> <hr/> <p>E-Mail Address: _____</p> <p>Phone Number: () _____ - _____ Ext. _____</p>	<p>Name/Title:</p> <hr/> <hr/> <hr/> <p>Signature: _____</p> <p>By submitting a response to this RFP, and signing above, Offeror acknowledges, understands and agrees to comply with the RFP requirements and confirms all the instructions and links have been read and understood.</p>
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*Indicates Bid Open Date change.